

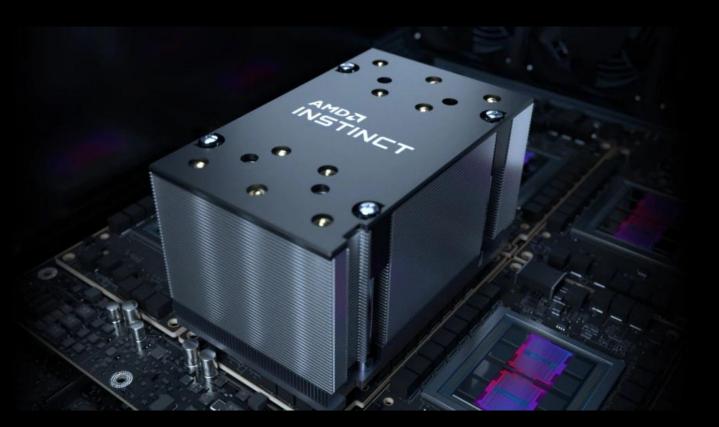
Recent Advances in UCX for AMD GPUs

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AMD together we advance_

Outline

- New ROCm features in UCX 1.15
- v2 protocols status update
- Non-temporal buffer transfers on "Zen 3"/"Zen 4" architectures
- Summary

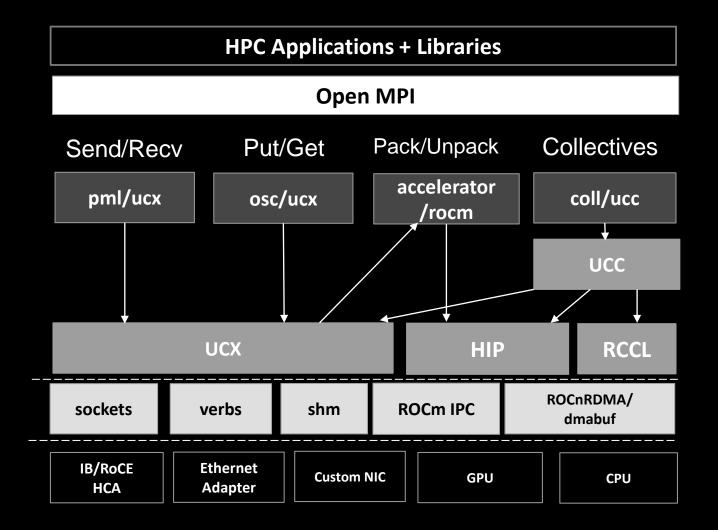


ROCm support in UCX

- ROCm/COPY: data transfer between host and device memory within a single process
- ROCm/IPC: data transfer between device memories of different processes on the same node
- GPUDirect RDMA for communication between processes on different nodes
- Memory type detection of ROCm memory
- Memory hooks for ROCm memory allocations

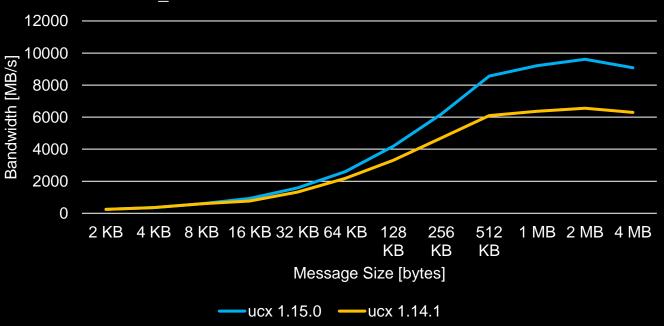
ROCm Aware Open MPI Software Stack with UCX and UCC

- Recommended
 software stack for
 InfiniBand and RoCE
 networks
- Most stable and best tested configuration



Asynchronous ROCm/copy zero-copy operations

- Allows to overlap multiple stages in some protocols
- Potential to improve device-to-host and host-to-device transfers
- Unified progress function for ROCm/copy and ROCm/ipc components



osu bw¹ for Device-to-Host transfers on MI250X

dma-buf support for ROCm devices

- dma-buf: Linux kernel subsystem providing a framework for sharing buffers across multiple devices
 - For example, RDMA capable network adaptor accessing a GPU device buffer
- Long-term replacement for the ROCnRDMA kernel component
- ROCm release 5.6 introduced functionality to export a device buffer for dma-buf sharing

dma-buf support for ROCm devices

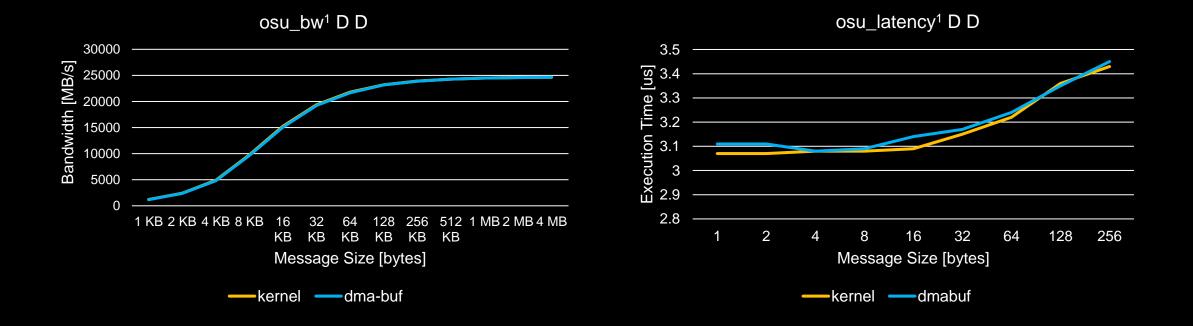
- Three components required to use dma-buf-based sharing for RDMA capable NICs
 - ROCm version with support for exporting dma-buf handle (hsa_amd_portable_export_dmabuf())
 - Version of the libibverbs that supports dma-buf-based memory registration (ibv_reg_dmabuf_mr())
 - Linux kernel with certain features enabled (CONFIG_DMABUF_MOVE_NOTIFY, CONFIG_PCI_P2PDMA)

dma-buf vs. ROCnRDMA kernel component

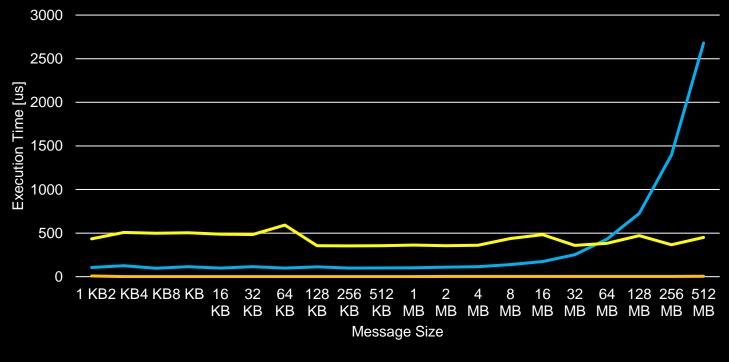
- 200Gb InfiniBand, mofed 5.9-0.5.6.0
- MI210 GPUs

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UCX 1.15.0, Open MPI 5.0, osu benchmarks 7.2.0



- Dma-buf vs. kernel component: registration costs
 - Ubuntu 22.04 with custom compiled Linux kernel 5.15
 - ROCm 5.7.1
 - mofed 5.9-0.5.6.0



----export_dmabuf -----ibv_reg_dmabuf_mr -----ibv_reg_mr

- Setting device_id for AMD GPUs
 - PCIe BDF for each GPU stored and can be used (e.g., for distance calculations)
 - Easier identification in debugging output
- Added logic for GPU assignment of ROCm memory domains
 - UCX uses internally the ROCm runtime layer functionality
 - Runtime layer does not have the notion of 'current device' that has been set (e.g. hipSetDevice())
 - Revamped logic allows to determine current device for some scenarios (interception of device allocation using memory hooks, HIP_VISIBLE_DEVICES)

v2 Protocols Status Update

- Intra-node correctness for ROCm device buffers
- Inter-node correctness for ROCm device buffers
- Intra-node performance for ROCm device buffers

 \checkmark

- Point-to-point
- Collectives (

 some overhead (20-50%) observed for short messages compared to ucx 1.15 for some collective operations
- Inter-node performance for ROCm device buffers
 - Point-to-point
 - RoCE
 - IB
 - Collectives
 - RoCE
 - IB

- still under investigation
- \checkmark

still under investigation



Non-Temporal Buffer Transfer

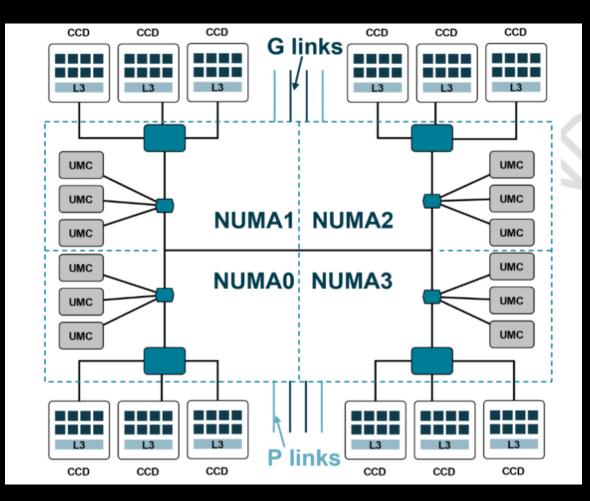
Hybrid MPI Applications on "Zen 3"/"Zen 4"

- Processors based on AMD's "Zen 3"/"Zen 4" architecture typically organize CPU cores into clusters of eight or more that share a common L3 cache(CCD).
- Hybrid MPI applications often employ 'n-ranks X mthreads' configuration

n <= Number of unified L3caches in system
 m >= Number of cores that share a common L3cache

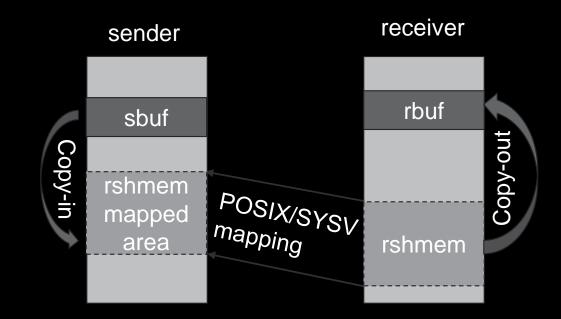
For example: 16 ranks X 8 OpenMP threads combination on a single "Milan" node

- Non-temporal buffer transfers try to improve the data transfer speed/application performance for such hybrid workloads.
- Communication libraries use copy-in, copy-out (shared memory) or single copy mechanisms to move data between ranks.
- Only UCX PML is considered for optimization here: https://github.com/openucx/ucx/pull/9408



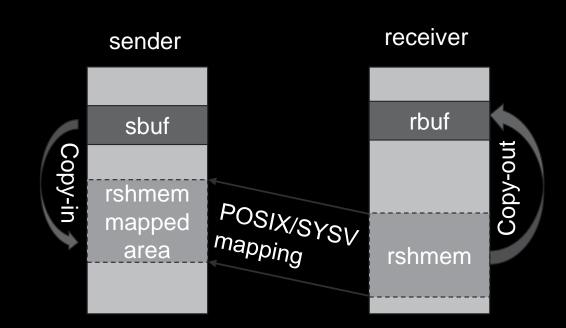
Handling UCX Copy-in, Copy-out (CICO)

- Non-temporal buffer transfer targets the hybrid workloads where sender and receiver do not share a common L3 cache (i.e., pinned to two different CCD)
- Use two distinct mechanism in place of glibc's memcpy for both copy-in and copy-out
 - New Copy-in routine:
 - Copy sender's buffer to receiver's shared memory
 - Use non-temporal store instead of normal store instructions while storing the data to shared memory destination
 - New Copy-out routine:
 - Copy from shared memory to receiver's buffer
 - Use 'Loads with PREFETCHNTA' instead of normal load instruction while loading from shared memory



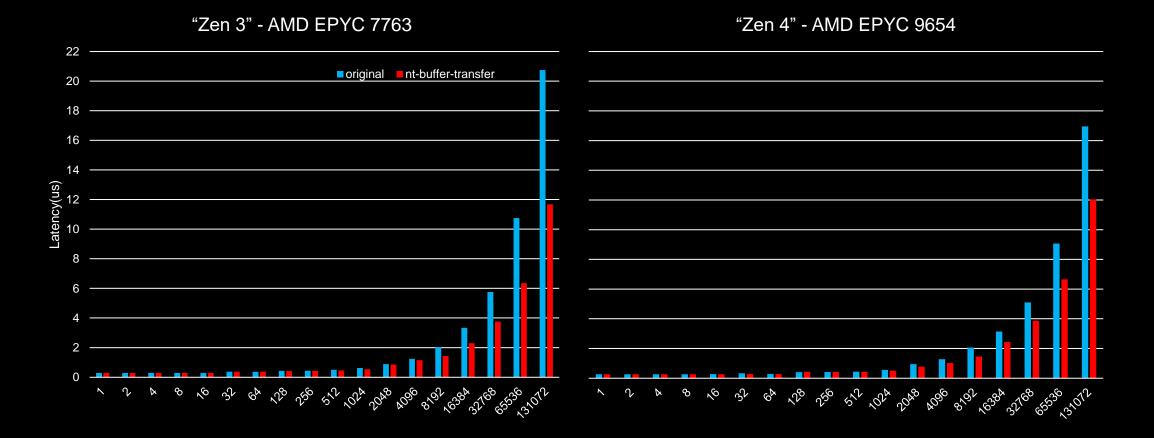
Handling UCX Copy-in, Copy-out (CICO)

- Advantages of using non-temporal load and store instruction
 - Reduces data transfer latency by circumventing cache-to-cache data transfers, which tend to be slower, when ranks/processes are situated in different CCD
 - Reduces the cache pollution, tends to keep only the application buffer in the caches





CICO osu_latency¹ Benchmark Results (map-by l3cache)



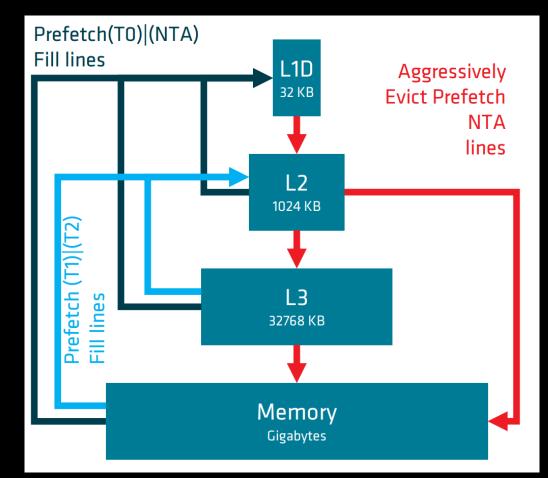
Gain: "Zen 3" up to 43 % @128 KB, "Zen 4" upto 28 % @128 KB

[1] OSU Benchmark Suite https://mvapich.cse.ohio-state.edu/benchmarks/ (BSD License).

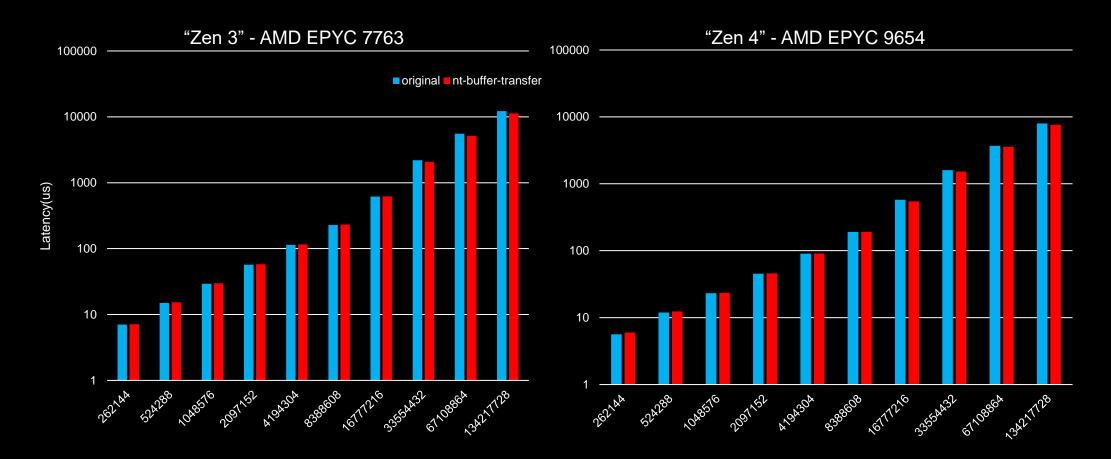


UCX Single Copy (SCOPY) Optimization

- Only xpmem is considered as it is the only single copy mechanism that uses memcpy in userspace
- The new method uses 'loads with PREFETCH NTA' instead of normal load instructions while copying from the sender
- It reduces cache pollution in the receiver
- The cache line bouncing effect in the sender is reduced for sizes less than L3 cache size



SCOPY osu_latency¹ Benchmark Results (map-by l3cache)



Gain: "Zen 3" 5-7 % for larger sizes, "Zen 4" 4-5 % for larger sizes

[1] OSU Benchmark Suite <u>https://mvapich.cse.ohio-state.edu/benchmarks/</u> (BSD License).



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